

Page 2 **BLOCK DIAGRAM**

Page 3 **SELF POWER + REGULATOR +FSD +LDO**

Page 4 **ANALOG FRONT END OPAMP +TEMP SENSOR**

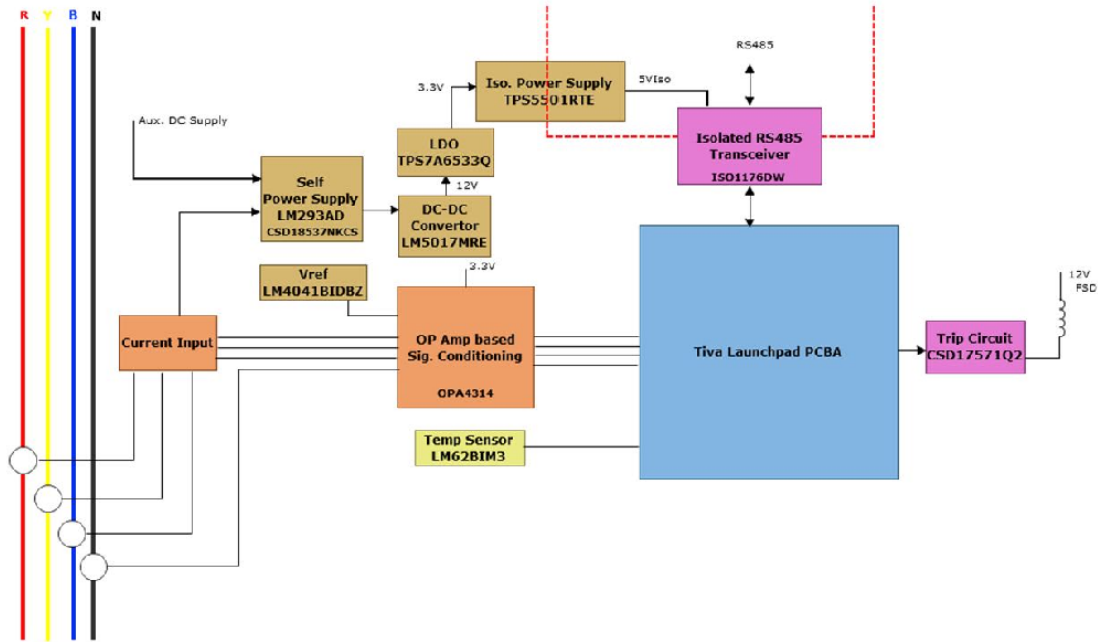
Page 5 **ISOLATED RS485 INTERFACE**

Page 6 **LAUNCH PAD INTERFACE**

Page 7 **HARDWARE - MISCELLANEOUS**

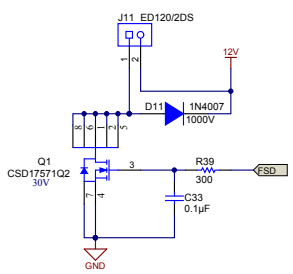
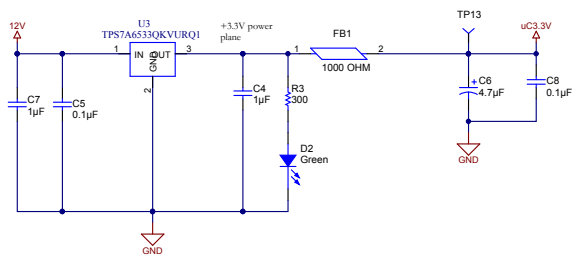
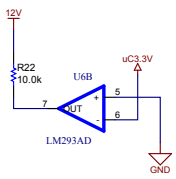
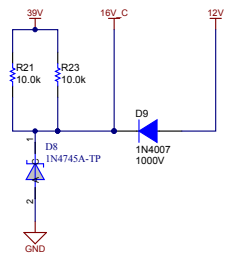
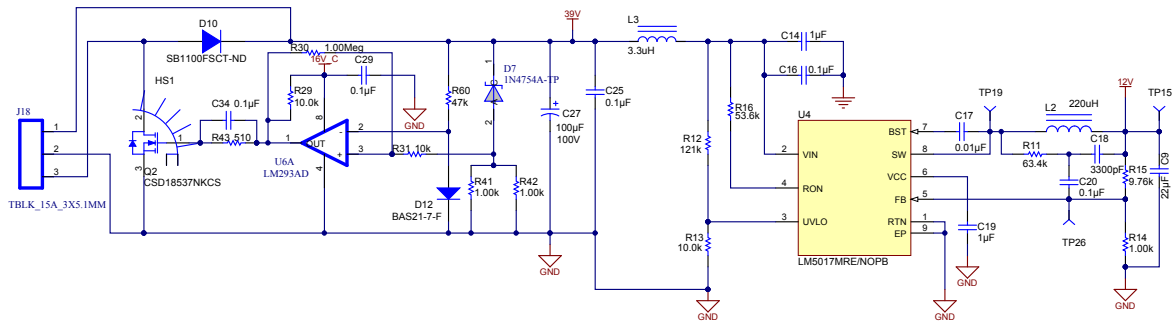
Revision History	
Revision	Notes





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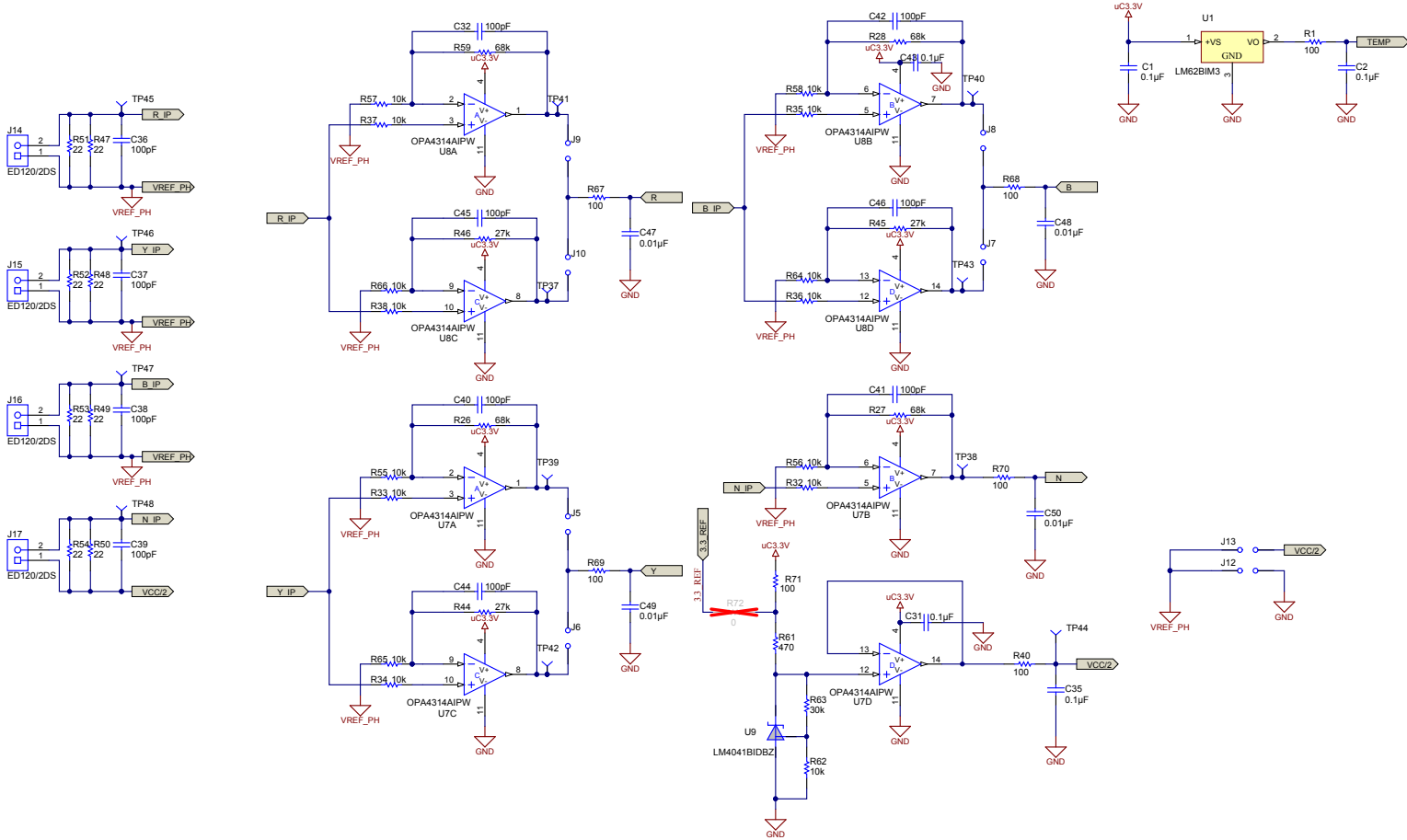
Number: TIDA-00128	Rev: E2	Designed for: Public Release	Mod. Date: 2/12/2014
SVN Rev.: Not in version control		Project Title: TIDA-00128 OPAMP BASED MCCB ETU	
Drawn By:		Assembly Variant: 001	Sheet: 2 of 7
Engineer: Enter name of project lead		File: Pcb Block Diagram.SchDoc	Size: B
		Contact: http://www.ti.com/support	

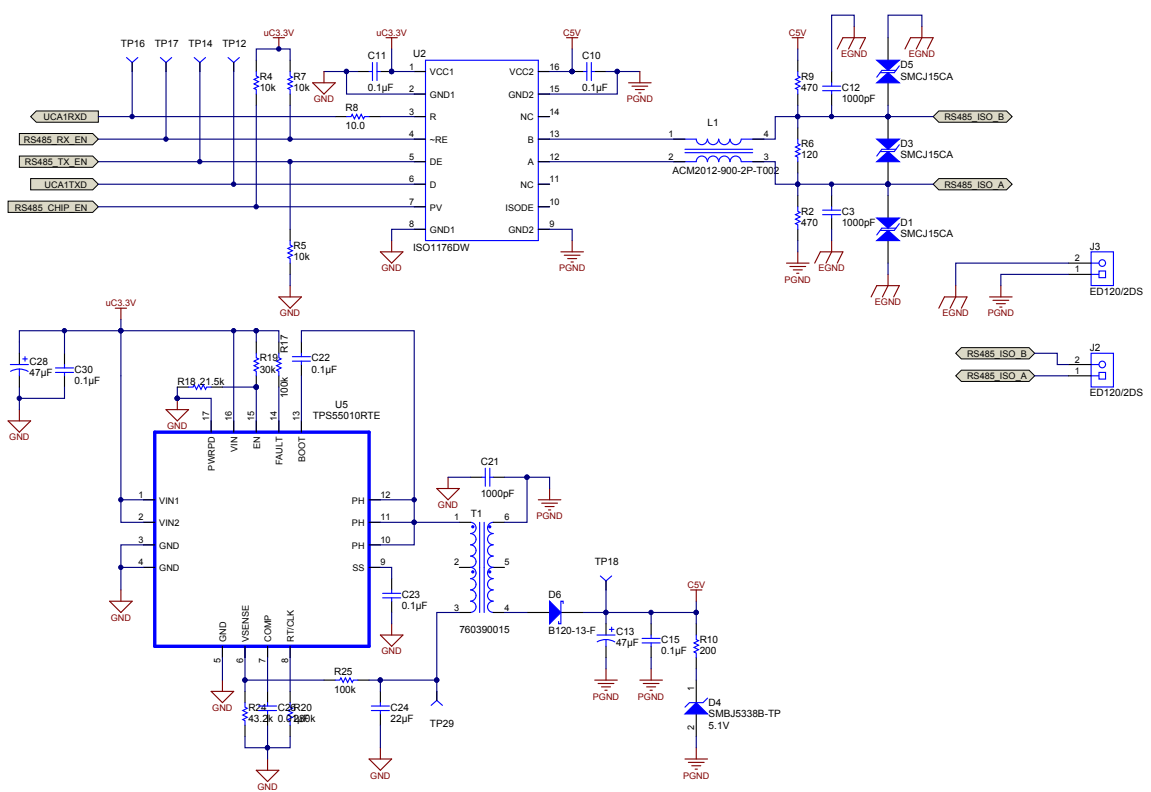


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SVN Rev.: Not in version control		Project Title: TIDA-00128 OPAMP BASED MCCB ETU	
Drawn By:		Sheet Title:	
Engineer: Enter name of project lead		Assembly Variant: 001	
Contact: http://www.ti.com/support		File: Pcb-Scp.Doc	
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		Size: B	



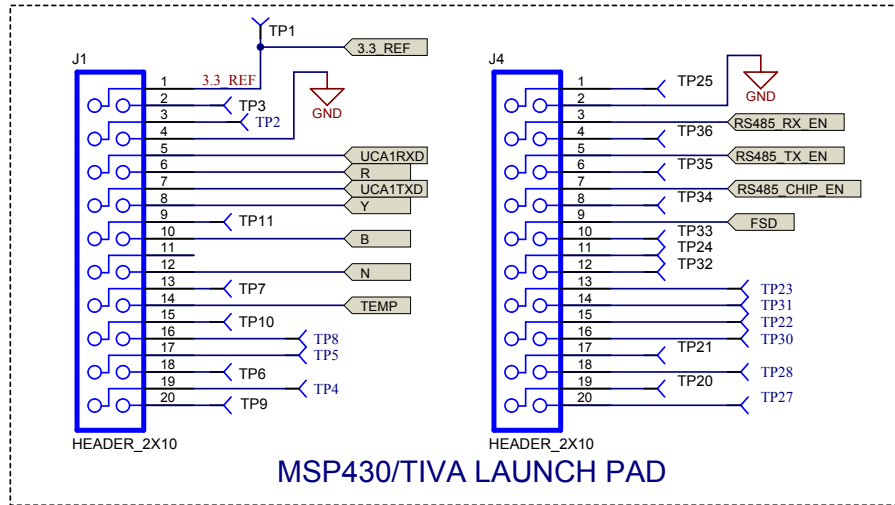




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Designed for: Public Release	Mod. Date: 1/28/2014
Project Title: TIDA-00128 OPAMP BASED MCCB ETU	
Number: TIDA-00128	Rev: E2
SVN Rev: Not in version control	Assembly Variant: 001
Drawn By:	File: Pds_Sch1.Doc
Engineer: Enter name of project lead	Contact: http://www.ti.com/support
Sheet Title:	Sheet: 5 of 7
	Size: B





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Number: TIDA-00128	Rev: E2	Designed for: Public Release	Mod. Date: 1/28/2014
SVN Rev: Not in version control	Drawn By:	Project Title: TIDA-00128 OPAMP BASED MCCB ETU	Sheet Title:
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	Assembly Variant: 001	Sheet: 6 of 7
		File: Pg6.SchDoc	Size: A4

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH H5 NY PMS 440 0025 PH

H7 1902C H6 1902C H9 1902C H8 1902C

MS
MH 3.2MM

FID2 FID1 FID3 FID6 FID5 FID4

PCB Number: TIDA-00128
PCB Rev: E2

PCB
LOGO
Texas Instruments

Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1

PCB Label

Size: 0.65" x 0.20"

Z21

Label Assembly Note

This Assembly Note is for PCB labels only

Z22

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: TIDA-00128	Rev: E2	Designed for: Public Release	Mod. Date: 1/28/2014
SVN Rev.: Not in version control	Assembly Variant: 001	Project Title: TIDA-00128 OPAMP BASED MCCB ETU	Sheet Title:
Drawn By:	File: P07_Hardware.SchDoc	Engineer: Enter name of project lead	Contact: http://www.ti.com/support

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